

RoHS

Key Features



- 2.5 dB Noise Figure
- 50.0 dBm Output IP₃
- 28.0 dB Gain
- 38.0 dBm P_{1dB}
- 1.3:1 VSWR
- 1.0/4.0 uS ON/OFF Timing
- TTL On/Off Control
- >34 Years MTBF
- **Unconditional Stable**
- **RoHS** Compliant

Specifications

Product Description

WPM0913C integrates WanTcom proprietary power amplifier technology, high frequency micro electronic assembly techniques, and high reliability design to realize optimum power added efficiency, wideband, high linearity, and unconditional stable performances together. With single +10.0V DC operation, the amplifier has optimal input and output matching in the specified frequency range at 50-Ohm impedance system. The amplifier has the gold plated standard flange package structure.

The amplifier is designed to meet the rugged standard of MIL-STD-202. Additional Heat Sink Is Required For Normal

operation!!

Summary of the electrical specifications WPM0913C at room temperature

| CAUTION: | |
|-----------------------------|--|
| $\mathbf{\hat{\mathbf{G}}}$ | |
| | |
| SENSITIVE | |

Applications

- Mobile Infrastructures
- GPS
- Security System •
- Defense
- Measurement
- Fixed Wireless

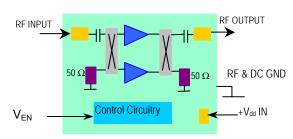


| Index | Testing Item | Symbol | Test Constraints | | Nom | Max | Unit |
|-------|---------------------------------------|----------------------|--|-----|---------|--------|-------|
| 1 | Gain | S ₂₁ | 0.95 – 1.3 GHz | | 28 | 30 | dB |
| 2 | Gain Variation | ΔG | 0.95 – 1.3 GHz | | +/- 0.3 | +/-0.5 | dB |
| 3 | Input VSWR | SWR ₁ | 0.95 – 1.3 GHz | | 1.3:1 | 1.5:1 | Ratio |
| 4 | Output VSWR | SWR ₂ | 0.95 – 1.3 GHz | | 1.3:1 | 1.5:1 | Ratio |
| 5 | Reverse Isolation | S ₁₂ | 0.95 – 1.3 GHz | 40 | 45 | | dB |
| 6 | Noise Figure | NF | 0.95 – 1.3 GHz | | 2.5 | 4.0 | dB |
| 7 | Output Power 1dB Compression Point | P _{1dB} | 0.95 – 1.3 GHz | 37 | 39 | | dBm |
| 8 | Output-Third-Order Interception Point | IP ₃ | Two-Tone, Pout +27 dBm each, 1 MHz separation | 45 | 50 | | dBm |
| 9 | Spurious | IMs | Po = 37 dBm, 0.95 – 1.3 GHz | | | | dBc |
| 10 | Power Added Efficiency | η | Po = 37 dBm, 0.95 – 1.3 GHz | 26 | | | % |
| 11 | Current Consumption | l _{dd} | V _{dd} = +10 V | | 1.8 | | Α |
| 12 | Power Supply Voltage | V _{dd} | | 9.7 | +10.0 | 11.0 | V |
| 13 | TTL On/Off Control | V | ON | 3.7 | 5.0 | 5.5 | V |
| 13 1 | | V _{EN} | OFF | NC | 0 | 0.2 | V |
| 14 | Turn ON Time | T _{ON} | 10 % to 90 % | | 1.0 | | uS |
| 15 | Turn OFF Time | T _{OFF} | 90% to 10 % | | 4.0 | | uS |
| 16 | Thermal Resistance | R _{th,c} | Junction to case, one last stage power transistor ¹ | | 5 | 8 | °C/W |
| 17 | Operating Temperature | T₀ | With sufficient heat dissipation | -40 | | +85 | °C |
| 18 | Maximum CW RF Input Power | P _{IN, MAX} | DC – 6.0 GHz | | | 20 | dBm |

Absolute Maximum Ratings

| Parameters | Units | Ratings |
|-------------------------|-------|------------|
| DC Power Supply Voltage | V | -0.5, 12.0 |
| Drain Current | Α | 2.0 |
| Total Power Dissipation | W | 20 |
| CW RF Input Power | dBm | 20 |
| Channel Temperature | °C | 150 |
| Storage Temperature | °C | -55 ~ 125 |
| Operating Temperature | °C | -40 ~ 85 |
| Thermal Resistance | °C/W | 8 |

Functional Block Diagram



Operation of this device above any one of these parameters may cause permanent damage.

¹ The maximum junction temperature is calculated by one last stage power transistor which is biased at 0.90A with 9.8V drain voltage. The total power dissipation is 8.8W and the total junction temperature increase is $8.8 \times 8 = 70 \text{ C}$ at the worst case.

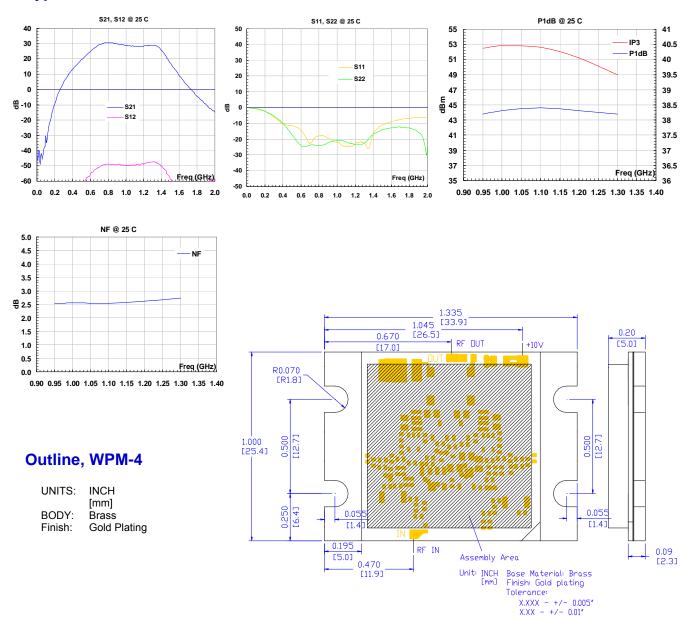
Specifications and information are subject to change without notice.



Ordering Information

| Model Number | WPM0913C |
|--------------|----------|
|--------------|----------|

Typical Data





Application Notes:

A. Mounting the Amplifier

Use four pieces of #4-40 with longer than 9/16" screws for mounting the amplifier on a metal-based chase. Flat and spring washers are needed to prevent the screw loosening during the shock and vibration. Always use the appropriate torque setting of the power screwdriver to mount them.

Always have stress release structure in the connection of the RF and DC I/Os to the system level.

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